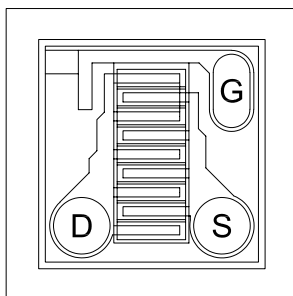


CP664V-2N2608

P-Channel JFET Die

The CP664V-2N2608 is a silicon P-Channel JFET designed for low level amplifier applications.



MECHANICAL SPECIFICATIONS:

Die Size	19 x 19 MILS
Die Thickness	7.9 MILS
Drain Bonding Pad Size	4.2 MILS DIAMETER
Source Bonding Pad Size	4.2 MILS DIAMETER
Gate Bonding Pad Size	2.9 x 5.3 MILS
Top Side Metalization	Al-Si – 17,000Å
Back Side Metalization	Au – 12,000Å
Scribe Alley Width	1.96 MILS
Wafer Diameter	5 INCHES
Gross Die Per Wafer	41,575

MAXIMUM RATINGS: (T_A=25°C)

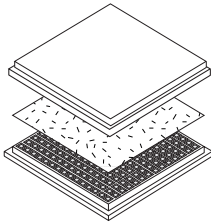
	SYMBOL		UNITS
Drain-Gate Voltage	V _{DG}	30	V
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	30	V
Continuous Gate Current	I _G	50	mA
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C

ELECTRICAL CHARACTERISTICS: (T_A=25°C unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I _{GSS}	V _{GS} =5.0V, V _{DS} =0		10	nA
I _{DSS} *	V _{DS} =5.0V, V _{GS} =0	0.9	4.5	mA
BV _{GSS}	I _G =1.0μA	30		V
V _{GS(OFF)}	V _{DS} =5.0V, I _D =1.0μA	1.0	4.0	V
y _{fs}	V _{DS} =5.0V, V _{GS} =0, f=1.0kHz	1.0K		μS
C _{iss}	V _{DS} =5.0V, V _{GS} =1.0V, f=140kHz		17	pF
NF	V _{DS} =5.0V, V _{GS} =0, f=1kHz, R _G =1.0MΩ, BW=1.0Hz		3.0	dB

*Pulse width < 100msec, Duty cycle <10%

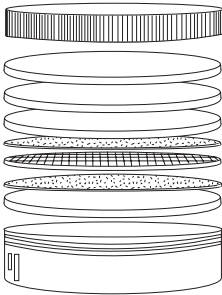
BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

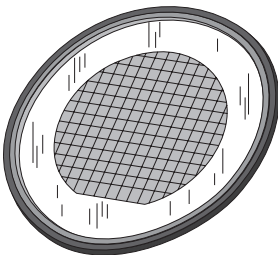
CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

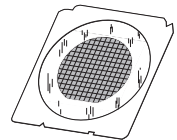
WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring,
100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centrasemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

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